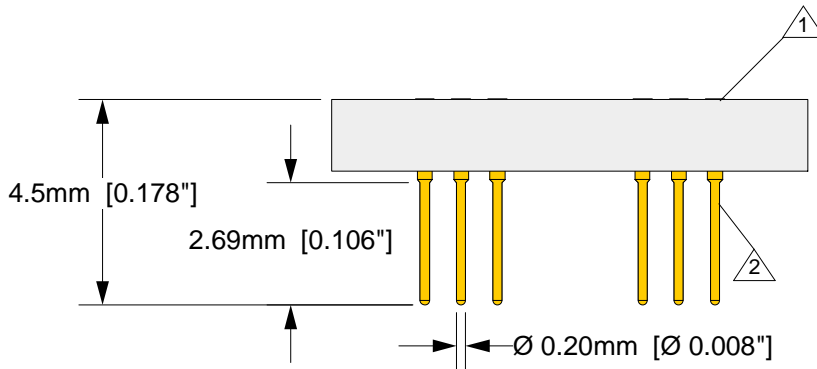


Top View




Side View

1 Substrate: 1.59mm \pm 0.18mm [0.062" \pm 0.007"]
FR4/G10 or equivalent high temp material.
Non-clad.

2 Pins: material- Brass Alloy 360 1/2 hard; finish-
0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.).

Description: Surface mount Foot
60 position BGA land socket.

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

LS-BGA60F-61 Drawing		Status: Released	Scale: 4:1	Rev: C
 <p>© 2006 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: H. Hansen		Date: 2/8/06	
	File: LS-BGA60F-61 Dwg		Modified: 07/01/14	